74LVC2T45-Q100; 74LVCH2T45-Q100

Dual supply translating transceiver; 3-state Rev. 3 — 28 January 2019

Product data sheet

1. General description

The 74LVC2T45-Q100; 74LVCH2T45-Q100 are dual bit, dual supply translating transceivers with 3-state outputs that enable bidirectional level translation. They feature two 2-bits input-output ports (nA and nB), a direction control input (DIR) and dual supply pins ($V_{CC(A)}$ and $V_{CC(B)}$). Both $V_{CC(A)}$ and $V_{CC(B)}$ can be supplied at any voltage between 1.2 V and 5.5 V making the device suitable for translating between any of the low voltage nodes (1.2 V, 1.5 V, 1.8 V, 2.5 V, 3.3 V and 5.0 V). Pins nA and DIR are referenced to $V_{CC(A)}$ and pins nB are referenced to $V_{CC(B)}$. A HIGH on DIR allows transmission from nA to nB and a LOW on DIR allows transmission from nB to nA.

The devices are fully specified for partial power-down applications using I_{OFF} . The I_{OFF} circuitry disables the output, preventing any damaging backflow current through the device when it is powered down. In suspend mode when either $V_{CC(A)}$ or $V_{CC(B)}$ are at GND level, both A port and B port are in the high-impedance OFF-state.

Active bus hold circuitry in the 74LVCH2T45-Q100 holds unused or floating data inputs at a valid logic level.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
 - Specified from -40 °C to +85 °C and from -40 °C to +125 °C
- Wide supply voltage range:
 - V_{CC(A)}: 1.2 V to 5.5 V
 - V_{CC(B)}: 1.2 V to 5.5 V
- High noise immunity
- Complies with JEDEC standards:
 - JESD8-7 (1.2 V to 1.95 V)
 - JESD8-5 (1.8 V to 2.7 V)
 - JESD8C (2.7 V to 3.6 V)
 - JESD36 (4.5 V to 5.5 V)
- ESD protection:
 - MIL-STD-883, method 3015 Class 3A exceeds 4000 V
 - HBM JESD22-A114F Class 3A exceeds 4000 V
 - MM JESD22-A115-A exceeds 200 V (C = 200 pF, R = 0 Ω)
- Maximum data rates:
 - 420 Mbps (3.3 V to 5.0 V translation)
 - 210 Mbps (translate to 3.3 V))
 - 140 Mbps (translate to 2.5 V)
 - 75 Mbps (translate to 1.8 V)
 - 60 Mbps (translate to 1.5 V)
- Suspend mode
- Latch-up performance exceeds 100 mA per JESD 78 Class II
- ± 24 mA output drive (V_{CC} = 3.0 V)
- Inputs accept voltages up to 5.5 V
- Low power consumption: 16 µA maximum I_{CC}

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IOFF circuitry provides partial Power-down mode operation

3. Ordering information

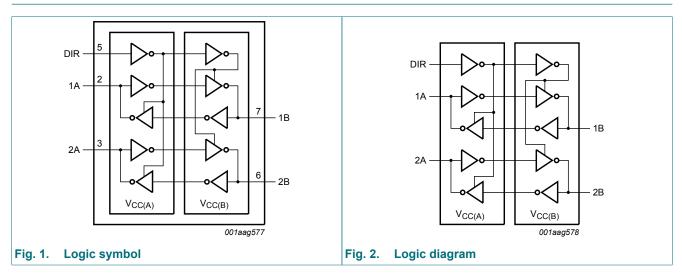
Type number	Package	Package							
	Temperature range	Name	Description	Version					
74LVC2T45DC-Q100	-40 °C to +125 °C	VSSOP8	plastic very thin shrink small outline package;	SOT765-1					
74LVCH2T45DC-Q100			8 leads; body width 2.3 mm						
74LVC2T45GT-Q100	-40 °C to +125 °C	XSON8	plastic extremely thin small outline package; no leads; 8 terminals; body 1 × 1.95 × 0.5 mm	SOT833-1					
74LVC2T45GS-Q100	-40 °C to +125 °C	XSON8	extremely thin small outline package; no leads; 8 terminals; body 1.35 × 1.0 × 0.35 mm	SOT1203					

4. Marking

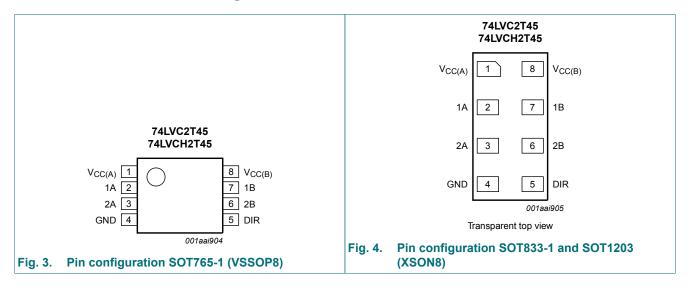
Table 2. Marking	Table 2. Marking							
Type number	Marking code [1]							
74LVC2T45DC-Q100	V45							
74LVCH2T45DC-Q100	X45							
74LVC2T45GT-Q100	V45							
74LVC2T45GS-Q100	V5							

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5. Functional diagram



6. Pinning information



6.1. Pinning

6.2. Pin description

Symbol	Pin	Description
V _{CC(A)}	1	supply voltage A (port A and DIR)
1A	2	data input or output
2A	3	data input or output
GND	4	ground (0 V)
DIR	5	direction control
2B	6	data input or output
1B	7	data input or output
V _{CC(B)}	8	supply voltage B (port B)

7. Functional description

Table 4. Function table

H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

Supply voltage	Input	Input/output [1]			
V _{CC(A)} , V _{CC(B)}	DIR	nA	nB		
1.2 V to 5.5 V	L	nA = nB	input		
1.2 V to 5.5 V	Н	input	nB = nA		
GND [2]	Х	Z	Z		

[1] The input circuit of the data I/O is always active.

[2] When either $V_{CC(A)}$ or $V_{CC(B)}$ is at GND level, the device goes into suspend mode.

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		Min	Max	Unit
V _{CC(A)}	supply voltage A			-0.5	+6.5	V
V _{CC(B)}	supply voltage B			-0.5	+6.5	V
I _{IK}	input clamping current	V _I < 0 V		-50	-	mA
VI	input voltage		[1]	-0.5	+6.5	V
I _{OK}	output clamping current	V _O < 0 V		-50	-	mA
Vo	output voltage	Active mode	[1][2][3]	-0.5	V _{CCO} + 0.5	V
		Suspend or 3-state mode	[1]	-0.5	+6.5	V
I _O	output current	$V_{O} = 0 V$ to V_{CCO}	[2]	-	±50	mA
I _{CC}	supply current	I _{CC(A)} or I _{CC(B)}		-	100	mA
I _{GND}	ground current			-100	-	mA
T _{stg}	storage temperature			-65	+150	°C
P _{tot}	total power dissipation	T_{amb} = -40 °C to +125 °C	[4]	-	250	mW

[1] The minimum input voltage ratings and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] V_{CCO} is the supply voltage associated with the output port.

[3] V_{CCO} + 0.5 V should not exceed 6.5 V.

[4] For VSSOP8 packages: above 110 °C the value of P_{tot} derates linearly with 8.0 mW/K. For XSON8 packages: above 118 °C the value of P_{tot} derates linearly with 7.8 mW/K.

9. Recommended operating conditions

Table 6. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Мах	Unit
V _{CC(A)}	supply voltage A		1.2	5.5	V
V _{CC(B)}	supply voltage B		1.2	5.5	V
VI	input voltage		0	5.5	V
Vo	output voltage	Active mode [1]	0	V _{cco}	V
		Suspend or 3-state mode	0	5.5	V
T _{amb}	ambient temperature		-40	+125	°C
Δt/ΔV	input transition rise and fall rate	V _{CCI} = 1.2 V [2]	-	20	ns/V
		V _{CCI} = 1.4 V to 1.95 V	-	20	ns/V
		V _{CCI} = 2.3 V to 2.7 V	-	20	ns/V
		V _{CCI} = 3 V to 3.6 V	-	10	ns/V
		V _{CCI} = 4.5 V to 5.5 V	-	5	ns/V

[1] V_{CCO} is the supply voltage associated with the output port.

[2] V_{CCI} is the supply voltage associated with the input port.

10. Static characteristics

Table 7. Typical static characteristics at T_{amb} = 25 °C

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		Min	Тур	Мах	Unit
V _{OH}	HIGH-level output voltage	$V_{I} = V_{IH} \text{ or } V_{IL}; I_{O} = -3 \text{ mA}; V_{CCO} = 1.2 \text{ V}$	[1]	-	1.09	-	V
V _{OL}	LOW-level output voltage	$V_I = V_{IH} \text{ or } V_{IL}; I_O = 3 \text{ mA}; V_{CCO} = 1.2 \text{ V}$	[1]	-	0.07	-	V
I _I	input leakage current	DIR input; V _I = 0 V to 5.5 V; V _{CCI} = 1.2 V to 5.5 V	[2]	-	-	±1	μA
I _{BHL}	bus hold LOW current	A or B port; V_1 = 0.42 V; V_{CC1} = 1.2 V	[2]	-	19	-	μA
I _{BHH}	bus hold HIGH current	A or B port; $V_1 = 0.78 V$; $V_{CCI} = 1.2 V$	[2]	-	-19	-	μA
I _{BHLO}	bus hold LOW overdrive current	A or B port; V _{CCI} = 1.2 V	[2][3]	-	19	-	μA
I _{BHHO}	bus hold HIGH overdrive current	A or B port; V _{CCI} = 1.2 V	[2][3]	-	-19	-	μA
I _{OZ}	OFF-state output current	A or B port; V _O = 0 V or V _{CCO} ; V _{CCO} = 1.2 V to 5.5 V	[1]	-	-	±1	μA
I _{OFF}	power-off leakage current	A port; V _I or V _O = 0 V to 5.5 V; V _{CC(A)} = 0 V; V _{CC(B)} = 1.2 V to 5.5 V		-	-	±1	μA
		B port; V _I or V _O = 0 V to 5.5 V; V _{CC(B)} = 0 V; V _{CC(A)} = 1.2 V to 5.5 V		-	-	±1	μA
CI	input capacitance	DIR input; $V_1 = 0 V \text{ or } 3.3 V$; $V_{CC(A)} = V_{CC(B)} = 3.3 V$		-	2.2	-	pF
C _{I/O}	input/output capacitance	A and B port; suspend mode; V _O = 3.3 V or 0 V; V _{CC(A)} = V _{CC(B)} = 3.3 V		-	6.0	-	pF

[1] V_{CCO} is the supply voltage associated with the output port.

[2] V_{CCI} is the supply voltage associated with the data input port.

[3] To guarantee the node switches, an external driver must source/sink at least I_{BHLO}/I_{BHHO} when the input is in the range V_{IL} to V_{IH} .

Table 8. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to	+85 °C	-40 °C to	+125 °C	Unit
				Мах	Min	Мах	
VIH	HIGH-level	data input [1]					
	input voltage	V _{CCI} = 1.2 V	0.8V _{CCI}	-	0.8V _{CCI}	-	V
		V _{CCI} = 1.4 V to 1.95 V	0.65V _{CCI}	-	0.65V _{CCI}	-	V
		V_{CCI} = 2.3 V to 2.7 V	1.7	-	1.7	-	V
		V _{CCI} = 3.0 V to 3.6 V	2.0	-	2.0	-	V
		V _{CCI} = 4.5 V to 5.5 V	0.7V _{CCI}	-	0.7V _{CCI}	-	V
		DIR input					
		V _{CCI} = 1.2 V	0.8V _{CC(A)}	-	0.8V _{CC(A)}	-	V
		V _{CCI} = 1.4 V to 1.95 V	0.65V _{CC(A)}	-	0.65V _{CC(A)}	-	V
		V _{CCI} = 2.3 V to 2.7 V	1.7	-	1.7	-	V
		V _{CCI} = 3.0 V to 3.6 V	2.0	-	2.0	-	V
		V_{CCI} = 4.5 V to 5.5 V	0.7V _{CC(A)}	-	0.7V _{CC(A)}	-	V

Symbol	Parameter	Conditions		-40 °C te	o +85 °C	-40 °C to	• +125 °C	Unit
				Min	Max	Min	Max	
V _{IL}	LOW-level input	data input	[1]					
	voltage	V _{CCI} = 1.2 V		-	0.2V _{CCI}	-	0.2V _{CCI}	V
		V _{CCI} = 1.4 V to 1.95 V		-	0.35V _{CCI}	-	0.35V _{CCI}	V
		V _{CCI} = 2.3 V to 2.7 V		-	0.7	-	0.7	V
		V _{CCI} = 3.0 V to 3.6 V		-	0.8	-	0.8	V
		V _{CCI} = 4.5 V to 5.5 V		-	0.3V _{CCI}	-	0.3V _{CCI}	V
		DIR input						
		V _{CCI} = 1.2 V		-	0.2V _{CC(A)}	-	0.2V _{CC(A)}	V
		V _{CCI} = 1.4 V to 1.95 V		-	0.35V _{CC(A)}	-	0.35V _{CC(A)}	V
		V _{CCI} = 2.3 V to 2.7 V		-	0.7	-	0.7	V
		V _{CCI} = 3.0 V to 3.6 V		-	0.8	-	0.8	V
		V _{CCI} = 4.5 V to 5.5 V		-	0.3V _{CC(A)}	-	0.3V _{CC(A)}	V
V _{OH}	HIGH-level	$V_{I} = V_{IH}$						
	output voltage	I _O = -100 μA; V _{CCO} = 1.2 V to 4.5 V	[2]	V _{CCO} - 0.1	-	V _{CCO} - 0.1	-	V
		I _O = -6 mA; V _{CCO} = 1.4 V		1.0	-	1.0	-	V
		I _O = -8 mA; V _{CCO} = 1.65 V		1.2	-	1.2	-	V
		I _O = -12 mA; V _{CCO} = 2.3 V		1.9	-	1.9	-	V
		I _O = -24 mA; V _{CCO} = 3.0 V		2.4	-	2.4	-	V
		I _O = -32 mA; V _{CCO} = 4.5 V		3.8	-	3.8	-	V
V _{OL}	LOW-level output voltage	$V_{I} = V_{IL}$	[2]					
		I _O = 100 μA; V _{CCO} = 1.2 V to 4.5 V		-	0.1	-	0.1	V
		I _O = 6 mA; V _{CCO} = 1.4 V		-	0.3	-	0.3	V
		I _O = 8 mA; V _{CCO} = 1.65 V		-	0.45	-	0.45	V
		I _O = 12 mA; V _{CCO} = 2.3 V		-	0.3	-	0.3	V
		I _O = 24 mA; V _{CCO} = 3.0 V		-	0.55	-	0.55	V
		I _O = 32 mA; V _{CCO} = 4.5 V		-	0.55	-	0.55	V
lı	input leakage current	DIR input; V _I = 0 V to 5.5 V; V _{CCI} = 1.2 V to 5.5 V		-	±2	-	±10	μA
I _{BHL}	bus hold LOW	A or B port	[1]					
	current	V _I = 0.49 V; V _{CCI} = 1.4 V		15	-	10	-	μA
		V _I = 0.58 V; V _{CCI} = 1.65 V		25	-	20	-	μA
		V _I = 0.70 V; V _{CCI} = 2.3 V		45	-	45	-	μA
		V _I = 0.80 V; V _{CCI} = 3.0 V		100	-	80	-	μA
		V _I = 1.35 V; V _{CCI} = 4.5 V		100	-	100	-	μA
I _{BHH}	bus hold HIGH	A or B port	[1]					
	current	V _I = 0.91 V; V _{CCI} = 1.4 V		-15	-	-10	-	μA
		V _I = 1.07 V; V _{CCI} = 1.65 V		-25	-	-20	-	μA
		V _I = 1.60 V; V _{CCI} = 2.3 V		-45	-	-45	-	μA
		V _I = 2.00 V; V _{CCI} = 3.0 V		-100	-	-80	-	μA
		V _I = 3.15 V; V _{CCI} = 4.5 V		-100	_	-100	_	μA

74LVC_LVCH2T45_Q100

Symbol	Parameter	Conditions	-40 °C t	o +85 °C	-40 °C to	• +125 °C	Unit
		-	Min	Max	Min	Мах	
I _{BHLO}	bus hold LOW	A or B port [1][3]					
	overdrive	V _{CCI} = 1.6 V	125	-	125	-	μA
	current	V _{CCI} = 1.95 V	200	-	200	-	μA
		V _{CCI} = 2.7 V	300	-	300	-	μA
		V _{CCI} = 3.6 V	500	-	500	-	μA
		V _{CCI} = 5.5 V	900	-	900	-	μA
I _{BHHO}	bus hold HIGH	A or B port [1][3]					
	overdrive	V _{CCI} = 1.6 V	-125	_	-125	_	μA
	current	V _{CCI} = 1.95 V	-200	_	-200	_	μA
		V _{CCI} = 2.7 V	-300	-	-300	-	μA
		V _{CCI} = 3.6 V	-500	-	-500	-	μA
		V _{CCI} = 5.5 V	-900	-	-900	-	μA
I _{OZ}	OFF-state output current	A or B port; $V_0 = 0$ V or V_{CCO} ; [2] $V_{CCO} = 1.2$ V to 5.5 V	-	±2	-	±10	μA
I _{OFF}	power-off leakage current	A port; V _I or V _O = 0 V to 5.5 V; V _{CC(A)} = 0 V; V _{CC(B)} = 1.2 V to 5.5 V	-	±2	-	±10	μA
		B port; V ₁ or V ₀ = 0 V to 5.5 V; V _{CC(B)} = 0 V; V _{CC(A)} = 1.2 V to 5.5 V	-	±2	-	±10	μA
I _{CC}	supply current	A port; $V_{I} = 0 V \text{ or } V_{CCI}$; $I_{O} = 0 A$ [1]					
		V _{CC(A)} , V _{CC(B)} = 1.2 V to 5.5 V	-	8	-	8	μA
		V _{CC(A)} , V _{CC(B)} = 1.65 V to 5.5 V	-	3	-	3	μA
		V _{CC(A)} = 5.5 V; V _{CC(B)} = 0 V	-	2	-	2	μA
		V _{CC(A)} = 0 V; V _{CC(B)} = 5.5 V	-2	-	-2	-	μA
		B port; $V_I = 0 V$ or V_{CCI} ; $I_O = 0 A$					
		V _{CC(A)} , V _{CC(B)} = 1.2 V to 5.5 V	-	8	-	8	μA
		V _{CC(A)} , V _{CC(B)} = 1.65 V to 5.5 V	-	3	-	3	μA
		V _{CC(B)} = 0 V; V _{CC(A)} = 5.5 V	-2	-	-2	-	μA
		V _{CC(B)} = 5.5 V; V _{CC(A)} = 0 V	-	2	-	2	μA
		A plus B port ($I_{CC(A)} + I_{CC(B)}$); $I_O = 0 A$; $V_I = 0 V \text{ or } V_{CCI}$					
		V _{CC(A)} , V _{CC(B)} = 1.2 V to 5.5 V	-	16	-	16	μA
		V _{CC(A)} , V _{CC(B)} = 1.65 V to 5.5 V	-	4	-	4	μA
ΔI _{CC}	additional supply current	per input; $V_{CC(A)}$, $V_{CC(B)}$ = 3.0 V to 5.5 V					
		A port; A port at $V_{CC(A)}$ - 0.6 V; [4] DIR at $V_{CC(A)}$; B port = open	-	50	-	75	μA
		DIR input; DIR at $V_{CC(A)}$ - 0.6 V; A port at $V_{CC(A)}$ or GND; B port = open	-	50	-	75	μA
		B port; B port at V _{CC(B)} - 0.6 V; [4] DIR at GND; A port = open	-	50	-	75	μA

 V_{CCI} is the supply voltage associated with the data input port. [1]

[2] [3]

 V_{CCO} is the supply voltage associated with the output port. To guarantee the node switches, an external driver must source/sink at least I_{BHLO}/I_{BHHO} when the input is in the range V_{IL} to V_{IH} .

[4] For non bus hold parts only (74LVC2T45-Q100).

11. Dynamic characteristics

Symbol	Parameter	Conditions			Vc	C(B)			Unit
			1.2 V	1.5 V	1.8 V	2.5 V	3.3 V	5.0 V	
t _{PLH}	LOW to HIGH propagation delay	A to B	10.6	8.1	7.0	5.8	5.3	5.1	ns
		B to A	10.6	9.5	9.0	8.5	8.3	8.2	ns
t _{PHL}	HIGH to LOW propagation delay	A to B	10.1	7.1	6.0	5.3	5.2	5.4	ns
		B to A	10.1	8.6	8.1	7.8	7.6	7.6	ns
t _{PHZ}	HIGH to OFF-state propagation delay	DIR to A	9.4	9.4	9.4	9.4	9.4	9.4	ns
		DIR to B	12.0	9.4	9.0	7.8	8.4	7.9	ns
t _{PLZ}	LOW to OFF-state	DIR to A	7.1	7.1	7.1	7.1	7.1	7.1	ns
	propagation delay	DIR to B	9.5	7.8	7.7	6.9	7.6	7.0	ns
t _{PZH}	OFF-state to HIGH	DIR to A [1]	20.1	17.3	16.7	15.4	15.9	15.2	ns
	propagation delay	DIR to B [1]	17.7	15.2	14.1	12.9	12.4	12.2	ns
t _{PZL}	OFF-state to LOW	DIR to A [1]	22.1	18.0	17.1	15.6	16.0	15.5	ns
	propagation delay	DIR to B [1]	19.5	16.5	15.4	14.7	14.6	14.8	ns

Table 9. Typical dynamic characteristics at V_{CC(A)} = 1.2 V and T_{amb} = 25 °C Voltages are referenced to GND (ground = 0 V); for test circuit see Fig. 7; for waveforms see Fig. 5 and Fig. 6.

[1] t_{PZH} and t_{PZL} are calculated values using the formula shown in <u>Section 13.4</u>.

Table 10. Typical dynamic characteristics at $V_{CC(B)}$ = 1.2 V and T_{amb} = 25 $^{\circ}C$

Voltages are referenced to GND (ground = 0 V); for test circuit see Fig. 7; for waveforms see Fig. 5 and Fig. 6.

Symbol	Parameter	Conditions			Vc	C(A)			Unit
			1.2 V	1.5 V	1.8 V	2.5 V	3.3 V	5.0 V	
t _{PLH}	LOW to HIGH	A to B	10.6	9.5	9.0	8.5	8.3	8.2	ns
	propagation delay	B to A	10.6	8.1	7.0	5.8	5.3	5.1	ns
t _{PHL}	HIGH to LOW	A to B	10.1	8.6	8.1	7.8	7.6	7.6	ns
	propagation delay	B to A	10.1	7.1	6.0	5.3	5.2	5.4	ns
t _{PHZ}	HIGH to OFF-state propagation delay	DIR to A	9.4	6.5	5.7	4.1	4.1	3.0	ns
		DIR to B	12.0	6.1	5.4	4.6	4.3	4.0	ns
t _{PLZ}	LOW to OFF-state	DIR to A	7.1	4.9	4.5	3.2	3.4	2.5	ns
	propagation delay	DIR to B	9.5	7.3	6.6	5.9	5.7	5.6	ns
t _{PZH}	OFF-state to HIGH	DIR to A [1]	20.1	15.4	13.6	11.7	11.0	10.7	ns
	propagation delay	DIR to B [1]	17.7	14.4	13.5	11.7	11.7	10.7	ns
t _{PZL}	OFF-state to LOW	DIR to A [1]	22.1	13.2	11.4	9.9	9.5	9.4	ns
	propagation delay	DIR to B [1]	19.5	15.1	13.8	11.9	11.7	10.6	ns

[1] t_{PZH} and t_{PZL} are calculated values using the formula shown in <u>Section 13.4</u>.

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Table 11. Typical power dissipation capacitance at $V_{CC(A)}$ = $V_{CC(B)}$ and T_{amb} = 25 $^{\circ}C$

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		V _{CC(A)} ar	nd V _{CC(B)}		Unit
			1.8 V	2.5 V	3.3 V	5.0 V	
C _{PD}	power dissipation capacitance[1] [2]	A port: (direction A to B); B port: (direction B to A)	2	3	3	4	pF
		A port: (direction A to B); B port: (direction B to A)	15	16	16	18	pF

[1] C_{PD} is used to determine the dynamic power dissipation (P_D in μ W).

 $P_{\rm D} = C_{\rm PD} \times V_{\rm CC}^2 \times f_{\rm i} \times N + \Sigma (C_{\rm L} \times V_{\rm CC}^2 \times f_{\rm o}) \text{ where:}$

f_i = input frequency in MHz;

 f_o = output frequency in MHz;

 C_L = load capacitance in pF;

V_{CC} = supply voltage in V;

N = number of inputs switching;

 $\Sigma(C_L \times V_{CC}^2 \times f_0)$ = sum of the outputs.

[2] $f_i = 10 \text{ MHz}$; $V_I = \text{GND}$ to V_{CC} ; $t_r = t_f = 1 \text{ ns}$; $C_L = 0 \text{ pF}$; $R_L = \infty \Omega$.

Table 12. Dynamic characteristics for temperature range -40 °C to +85 °C

Voltages are referenced to GND (ground = 0 V); for test circuit see $\underline{Fig. 7}$; for waveforms see $\underline{Fig. 5}$ and $\underline{Fig. 6}$.

Symbol	Parameter	Conditions					Vcc	;(B)					Unit
			1.5 V :	± 0.1 V	1.8 V ±	: 0.15 V	2.5 V :	± 0.2 V	3.3 V :	± 0.3 V	5.0 V ±	± 0.5 V	
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
V _{CC(A)} =	1.4 V to 1.6 V		1						1				
t _{PLH}	LOW to HIGH	A to B	2.8	21.3	2.4	17.6	2.0	13.5	1.7	11.8	1.6	10.5	ns
	propagation delay	B to A	2.8	21.3	2.6	19.1	2.3	14.9	2.3	12.4	2.2	12.0	ns
t _{PHL}	HIGH to LOW	A to B	2.6	19.3	2.2	15.3	1.8	11.8	1.7	10.9	1.7	10.8	ns
	propagation delay	B to A	2.6	19.3	2.4	17.3	2.3	13.2	2.2	11.3	2.3	11.0	ns
t _{PHZ}	HIGH to OFF-state	DIR to A	3.0	18.7	3.0	18.7	3.0	18.7	3.0	18.7	3.0	18.7	ns
	propagation delay	DIR to B	3.5	24.8	3.5	23.6	3.0	11.0	3.3	11.3	2.8	10.3	ns
t _{PLZ}	LOW to OFF-state	DIR to A	2.4	11.4	2.4	11.4	2.4	11.4	2.4	11.4	2.4	11.4	ns
	propagation delay	DIR to B	2.8	18.3	3.0	17.2	2.5	9.4	3.0	10.1	2.5	9.4	ns
t _{PZH}	OFF-state to HIGH	DIR to A [1]	-	39.6	-	36.3	-	24.3	-	22.5	-	21.4	ns
	propagation delay	DIR to B [1]	-	32.7	-	29.0	-	24.9	-	23.2	-	21.9	ns
t _{PZL}	OFF-state to LOW	DIR to A [1]	-	44.1	-	40.9	-	24.2	-	22.6	-	21.3	ns
	propagation delay	DIR to B [1]	-	38.0	-	34.0	-	30.5	-	29.6	-	29.5	ns

Symbol	Parameter	Conditions					Vcc	C(B)					Unit
			1.5 V	± 0.1 V	1.8 V ±	: 0.15 V		± 0.2 V	3.3 V	± 0.3 V	5.0 V :	± 0.5 V	
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
V _{CC(A)} =	1.65 V to 1.95 V	1	<u> </u>	1						1			
t _{PLH}	LOW to HIGH	A to B	2.6	19.1	2.2	17.7	2.2	9.3	1.7	7.2	1.4	6.8	ns
	propagation delay	B to A	2.4	17.6	2.2	17.7	2.3	16.0	2.1	15.5	1.9	15.1	ns
t _{PHL}	HIGH to LOW	A to B	2.4	17.3	2.0	14.3	1.6	8.5	1.8	7.1	1.7	7.0	ns
	propagation delay	B to A	2.2	15.3	2.0	14.3	2.1	12.9	2.0	12.6	1.8	12.2	ns
t _{PHZ}	HIGH to OFF-state	DIR to A	2.9	17.1	2.9	17.1	2.9	17.1	2.9	17.1	2.9	17.1	ns
	propagation delay	DIR to B	3.2	24.1	3.2	21.9	2.7	11.5	3.0	10.3	2.5	8.2	ns
t _{PLZ}	LOW to OFF-state	DIR to A	2.4	10.5	2.4	10.5	2.4	10.5	2.4	10.5	2.4	10.5	ns
	propagation delay	DIR to B	2.5	17.6	2.6	16.0	2.2	9.2	2.7	8.4	2.4	7.1	ns
t _{PZH}	OFF-state to HIGH	DIR to A [1]	-	35.2	-	33.7	-	25.2	-	23.9	-	22.2	ns
	propagation delay	DIR to B [1]	-	29.6	-	28.2	-	19.8	-	17.7	-	17.3	ns
t _{PZL}	OFF-state to LOW	DIR to A [1]	-	39.4	-	36.2	-	24.4	-	22.9	-	20.4	ns
	propagation delay	DIR to B [1]	-	34.4	-	31.4	-	25.6	-	24.2	-	24.1	ns
$V_{CC(A)} =$	2.3 V to 2.7 V												
t _{PLH}	LOW to HIGH	A to B	2.3	17.9	2.3	16.0	1.5	8.5	1.3	6.2	1.1	4.8	ns
	propagation delay	B to A	2.0	13.5	2.2	9.3	1.5	8.5	1.4	8.0	1.0	7.5	ns
t _{PHL}	HIGH to LOW	A to B	2.3	15.8	2.1	12.9	1.4	7.5	1.3	5.4	0.9	4.6	ns
	propagation delay	B to A	1.8	11.8	1.9	8.5	1.4	7.5	1.3	7.0	0.9	6.2	ns
t _{PHZ}	HIGH to OFF-state	DIR to A	2.1	8.1	2.1	8.1	2.1	8.1	2.1	8.1	2.1	8.1	ns
	propagation delay	DIR to B	3.0	22.5	3.0	21.4	2.5	11.0	2.8	9.3	2.3	6.9	ns
t _{PLZ}	LOW to OFF-state	DIR to A	1.7	5.8	1.7	5.8	1.7	5.8	1.7	5.8	1.7	5.8	ns
	propagation delay	DIR to B	2.3	14.6	2.5	13.2	2.0	9.0	2.5	8.4	1.8	5.8	ns
t _{PZH}	OFF-state to HIGH	DIR to A [1]	-	28.1	-	22.5	-	17.5	-	16.4	-	13.3	ns
	propagation delay	DIR to B [1]	-	23.7	-	21.8	-	14.3	-	12.0	-	10.6	ns
t _{PZL}	OFF-state to LOW	DIR to A [1]	-	34.3	-	29.9	-	18.5	-	16.3	-	13.1	ns
	propagation delay	DIR to B [1]	-	23.9	-	21.0	-	15.6	-	13.5	-	12.7	ns
$V_{CC(A)} =$	3.0 V to 3.6 V	1											
t _{PLH}	LOW to HIGH	A to B	2.3	17.1	2.1	15.5	1.4	8.0	0.8	5.6	0.7	4.4	ns
	propagation delay	B to A	1.7	11.8	1.7	7.2	1.3	6.2	0.7	5.6	0.6	5.4	ns
t _{PHL}	HIGH to LOW	A to B	2.2	15.6	2.0	12.6	1.3	7.0	0.8	5.0	0.7	4.0	ns
	propagation delay	B to A	1.7	10.9	1.8	7.1	1.3	5.4	0.8	5.0	0.7	4.5	ns
t _{PHZ}	HIGH to OFF-state	DIR to A	2.3	7.3	2.3	7.3	2.3	7.3	2.3	7.3	2.7	7.3	ns
	propagation delay	DIR to B	2.9	18.0	2.9	16.5	2.3	10.1	2.7	8.6	2.2	6.3	ns
t _{PLZ}	LOW to OFF-state	DIR to A	2.0	5.6	2.0	5.6	2.0	5.6	2.0	5.6	2.0	5.6	ns
	propagation delay	DIR to B	2.3	13.6	2.4	12.5	1.9	7.8	2.3	7.1	1.7	4.9	ns
t _{PZH}	OFF-state to HIGH	DIR to A [1]	-	25.4	-	19.7	-	14.0	-	12.7	-	10.3	ns
	propagation delay	DIR to B [1]	-	22.7	-	21.1	-	13.6	-	11.2	-	10.0	ns
t _{PZL}	OFF-state to LOW	DIR to A [1]	-	28.9	-	23.6	-	15.5	-	13.6	-	10.8	ns
	propagation delay	DIR to B [1]	-	22.9	-	19.9	-	14.3	-	12.3	-	11.3	ns

Symbol	Parameter	Conditions					Vcc	:(B)					Unit
			1.5 V :	± 0.1 V	1.8 V ±	0.15 V	2.5 V :	± 0.2 V	3.3 V :	± 0.3 V	5.0 V ±	± 0.5 V	
			Min	Max	Min	Мах	Min	Max	Min	Max	Min	Max	
$V_{CC(A)} =$	4.5 V to 5.5 V		1						1			1	
t _{PLH}	LOW to HIGH	A to B	2.2	16.6	1.9	15.1	1.0	7.5	0.7	5.4	0.5	3.9	ns
	propagation delay	B to A	1.6	10.5	1.4	6.8	1.0	4.8	0.7	4.4	0.5	3.9	ns
t _{PHL}	HIGH to LOW	A to B	2.3	15.3	1.8	12.2	1.0	6.2	0.7	4.5	0.5	3.5	ns
propagation delay	B to A	1.7	10.8	1.7	7.0	0.9	4.6	0.7	4.0	0.5	3.5	ns	
t _{PHZ}	HIGH to OFF-state	DIR to A	1.7	5.4	1.7	5.4	1.7	5.4	1.7	5.4	1.7	5.4	ns
	propagation delay	DIR to B	2.9	17.3	2.9	16.1	2.3	9.7	2.7	8.0	2.5	5.7	ns
t _{PLZ}	LOW to OFF-state	DIR to A	1.4	3.7	1.4	3.7	1.3	3.7	1.0	3.7	0.9	3.7	ns
	propagation delay	DIR to B	2.3	13.1	2.4	12.1	1.9	7.4	2.3	7.0	1.8	4.5	ns
t _{PZH}	OFF-state to HIGH	DIR to A [1]	-	23.6	-	18.9	-	12.2	-	11.4	-	8.4	ns
	propagation delay	DIR to B [1]	-	20.3	-	18.8	-	11.2	-	9.1	-	7.6	ns
t _{PZL}	OFF-state to LOW	DIR to A [1]	-	28.1	-	23.1	-	14.3	-	12.0	-	9.2	ns
	propagation delay	DIR to B [1]	-	20.7	-	17.6	-	11.6	-	9.9	-	8.9	ns

[1] t_{PZH} and t_{PZL} are calculated values using the formula shown in <u>Section 13.4</u>.

Table 13. Dynamic characteristics for temperature range -40 °C to +125 °C

Voltages are referenced to GND (ground = 0 V); for test circuit see $\underline{Fig. 7}$; for waveforms see $\underline{Fig. 5}$ and $\underline{Fig. 6}$.

Symbol	Parameter	Conditions					Vcc	(B)					Unit
			1.5 V :	± 0.1 V	1.8 V ±	0.15 V	2.5 V :	± 0.2 V	3.3 V :	± 0.3 V	5.0 V :	± 0.5 V	
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
V _{CC(A)} =	1.4 V to 1.6 V												
t _{PLH}	LOW to HIGH	A to B	2.5	23.5	2.1	19.4	1.8	14.9	1.5	13.0	1.4	11.6	ns
	propagation delay	B to A	2.5	23.5	2.3	21.1	2.0	16.4	2.0	13.7	1.9	13.2	ns
t _{PHL}	HIGH to LOW	A to B	2.3	21.3	1.9	16.9	1.6	13.0	1.5	12.0	1.5	11.9	ns
propagation delay	propagation delay	B to A	2.3	21.3	2.1	19.1	2.0	14.6	1.9	12.5	2.0	12.1	ns
t _{PHZ}	HIGH to OFF-state	DIR to A	2.7	20.6	2.7	20.6	2.7	20.6	2.7	20.6	2.7	20.6	ns
	propagation delay	DIR to B	3.1	27.3	3.1	26.0	2.7	12.1	2.9	12.5	2.5	11.4	ns
t _{PLZ}	LOW to OFF-state	DIR to A	2.1	12.6	2.1	12.6	2.1	12.6	2.1	12.6	2.1	12.6	ns
	propagation delay	DIR to B	2.5	20.2	2.7	19.0	2.2	10.4	2.7	11.2	2.2	10.4	ns
t _{PZH}	OFF-state to HIGH	DIR to A [1]	-	43.7	-	40.1	-	26.8	-	24.9	-	23.6	ns
	propagation delay	DIR to B [1]	-	36.1	-	32.0	-	27.5	-	25.6	-	24.2	ns
t _{PZL}	OFF-state to LOW	DIR to A [1]	-	48.6	-	45.1	-	26.7	-	25.0	-	23.5	ns
	propagation delay	DIR to B [1]	-	41.9	-	37.5	-	33.6	-	32.6	-	32.5	ns

Symbol	Parameter	Conditions					Vcc	;(B)					Unit
			1.5 V	± 0.1 V	1.8 V ±	: 0.15 V		± 0.2 V	3.3 V	± 0.3 V	5.0 V :	± 0.5 V	
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
V _{CC(A)} =	1.65 V to 1.95 V		1	1		1		1	1			1	1
t _{PLH}	LOW to HIGH	A to B	2.3	21.1	1.9	19.5	1.9	10.3	1.5	8.0	1.2	7.5	ns
	propagation delay	B to A	2.1	19.4	1.9	19.5	2.0	17.6	1.8	17.1	1.7	16.7	ns
t _{PHL}	HIGH to LOW	A to B	2.1	19.1	1.8	15.8	1.4	9.4	1.6	7.9	1.5	7.7	ns
	propagation delay	B to A	1.9	16.9	1.8	15.8	1.8	14.2	1.8	13.9	1.6	13.5	ns
t _{PHZ}	HIGH to OFF-state	DIR to A	2.6	18.9	2.6	18.9	2.6	18.9	2.6	18.9	2.6	18.9	ns
	propagation delay	DIR to B	2.8	26.6	2.8	24.1	2.4	12.7	2.7	11.4	2.2	9.1	ns
t _{PLZ}	LOW to OFF-state	DIR to A	2.1	11.6	2.1	11.6	2.1	11.6	2.1	11.6	2.1	11.6	ns
	propagation delay	DIR to B	2.2	19.4	2.3	17.6	1.9	10.2	2.4	9.3	2.1	7.9	ns
t _{PZH}	OFF-state to HIGH	DIR to A [1]	-	38.8	-	37.1	-	27.8	-	26.4	-	24.6	ns
	propagation delay	DIR to B [1]	-	32.7	-	31.1	-	21.9	-	19.6	-	19.1	ns
t _{PZL}	OFF-state to LOW	DIR to A [1]	-	43.5	-	39.9	-	26.9	-	25.3	-	22.6	ns
	propagation delay	DIR to B [1]	-	38.0	-	34.7	-	28.3	-	26.8	-	26.6	ns
$V_{CC(A)} =$	2.3 V to 2.7 V												
t _{PLH}	LOW to HIGH	A to B	2.0	19.7	2.0	17.6	1.3	9.4	1.1	6.9	0.9	5.3	ns
	propagation delay	B to A	1.8	14.9	1.9	10.3	1.3	9.4	1.2	8.8	0.9	8.3	ns
t _{PHL}	HIGH to LOW	A to B	2.0	17.4	1.8	14.2	1.2	8.3	1.1	6.0	0.8	5.1	ns
	propagation delay	B to A	1.6	13.0	1.7	9.4	1.2	8.3	1.1	7.7	0.8	6.9	ns
t _{PHZ}	HIGH to OFF-state	DIR to A	1.8	9.0	1.8	9.0	1.8	9.0	1.8	9.0	1.8	9.0	ns
	propagation delay	DIR to B	2.7	24.8	2.7	23.6	2.2	12.1	2.5	10.3	2.0	7.6	ns
t _{PLZ}	LOW to OFF-state	DIR to A	1.5	6.4	1.5	6.4	1.5	6.4	1.5	6.4	1.5	6.4	ns
	propagation delay	DIR to B	2.0	16.1	2.2	14.6	1.8	9.9	2.2	9.3	1.6	6.4	ns
t _{PZH}	OFF-state to HIGH	DIR to A [1]	-	31.0	-	24.9	-	19.3	-	18.1	-	14.7	ns
	propagation delay	DIR to B [1]	-	26.1	-	24.0	-	15.8	-	13.3	-	11.7	ns
t _{PZL}	OFF-state to LOW	DIR to A [1]	-	37.8	-	33.0	-	20.4	-	18.0	-	14.5	ns
	propagation delay	DIR to B [1]	-	26.4	-	23.2	-	17.3	-	15.0	-	14.1	ns
$V_{CC(A)} =$	3.0 V to 3.6 V												
t _{PLH}	LOW to HIGH	A to B	2.0	18.9	1.8	17.1	1.2	8.8	0.7	6.2	0.6	4.9	ns
	propagation delay	B to A	1.5	13.0	1.5	8.0	1.1	6.9	0.6	6.2	0.5	6.0	ns
t _{PHL}	HIGH to LOW	A to B	1.9	17.2	1.8	13.9	1.1	7.7	0.7	5.5	0.6	4.4	ns
	propagation delay	B to A	1.5	12.0	1.6	7.9	1.1	6.0	0.7	5.5	0.6	5.0	ns
t _{PHZ}	HIGH to OFF-state	DIR to A	2.0	8.1	2.0	8.1	2.0	8.1	2.0	8.1	2.4	8.1	ns
	propagation delay	DIR to B	2.6	19.8	2.6	18.2	2.0	11.2	2.4	9.5	1.9	7.0	ns
t _{PLZ}	LOW to OFF-state	DIR to A	1.8	6.2	1.8	6.2	1.8	6.2	1.8	6.2	1.8	6.2	ns
	propagation delay	DIR to B	2.0	15.0	2.1	13.8	1.7	8.6	2.0	7.9	1.5	5.4	ns
t _{PZH}	OFF-state to HIGH	DIR to A [1]		28.0	-	21.8	-	15.5	-	14.1	-	11.4	ns
	propagation delay	DIR to B [1]	-	25.1	-	23.3	-	15.0	-	12.4	-	11.1	ns
t _{PZL}	OFF-state to LOW	DIR to A [1]		31.8	-	26.1	-	17.2	-	15.0	-	12.0	ns
	propagation delay	DIR to B [1]	-	25.3	-	22.0	-	15.8	-	13.6	-	12.5	ns

Symbol	Parameter	Conditions					Vcc	;(B)					Unit
			1.5 V :	± 0.1 V	1.8 V ±	0.15 V	2.5 V :	± 0.2 V	3.3 V :	± 0.3 V	5.0 V :	± 0.5 V	
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
V _{CC(A)} =	4.5 V to 5.5 V								1				
t _{PLH}	LOW to HIGH	A to B	1.9	18.3	1.7	16.7	0.9	8.3	0.6	6.0	0.4	4.3	ns
	propagation delay	B to A	1.4	11.6	1.2	7.5	0.9	5.3	0.6	4.9	0.4	4.3	ns
t _{PHL}	HIGH to LOW	A to B	2.0	16.9	1.6	13.5	0.9	6.9	0.6	5.0	0.4	3.9	ns
propagation delay	B to A	1.5	11.9	1.5	7.7	0.8	5.1	0.6	4.4	0.4	3.9	ns	
t _{PHZ}	HIGH to OFF-state	DIR to A	1.5	6.0	1.5	6.0	1.5	6.0	1.5	6.0	1.5	6.0	ns
	propagation delay	DIR to B	2.6	19.1	2.6	17.8	2.0	10.7	2.4	8.8	2.2	6.3	ns
t _{PLZ}	LOW to OFF-state	DIR to A	1.2	4.1	1.2	4.1	1.1	4.1	0.9	4.1	0.8	4.1	ns
	propagation delay	DIR to B	2.0	14.5	2.1	13.4	1.7	8.2	2.0	7.7	1.6	5.0	ns
t _{PZH}	OFF-state to HIGH	DIR to A [1]	-	26.1	-	20.9	-	13.5	-	12.6	-	9.3	ns
	propagation delay	DIR to B [1]	-	22.4	-	20.8	-	12.4	-	10.1	-	8.4	ns
t _{PZL}	OFF-state to LOW	DIR to A [1]	-	31.0	-	25.5	-	15.8	-	13.2	-	10.2	ns
	propagation delay	DIR to B [1]	-	22.9	-	19.5	-	12.9	-	11.0	-	9.9	ns

[1] t_{PZH} and t_{PZL} are calculated values using the formula shown in <u>Section 13.4</u>.

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11.1. Waveforms and test circuit

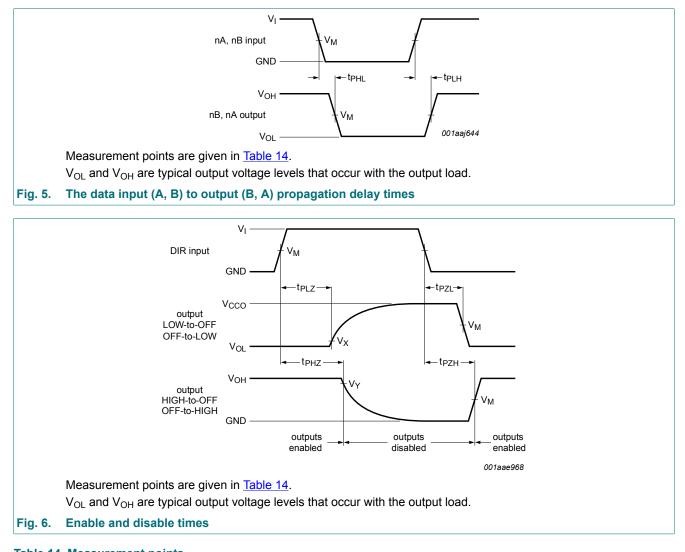


Table 14. Measurement points				
Supply voltage	Input [1]	Output [2]		
V _{CC(A)} , V _{CC(B)}	V _M	V _M	V _X	V _Y
1.2 V to 1.6 V	0.5V _{CCI}	0.5V _{CCO}	V _{OL} + 0.1 V	V _{OH} - 0.1 V
1.65 V to 2.7 V	0.5V _{CCI}	0.5V _{CCO}	V _{OL} + 0.15 V	V _{OH} - 0.15 V
3.0 V to 5.5 V	0.5V _{CCI}	0.5V _{CCO}	V _{OL} + 0.3 V	V _{OH} - 0.3 V

[1] V_{CCI} is the supply voltage associated with the data input port.

[2] V_{CCO} is the supply voltage associated with the output port.

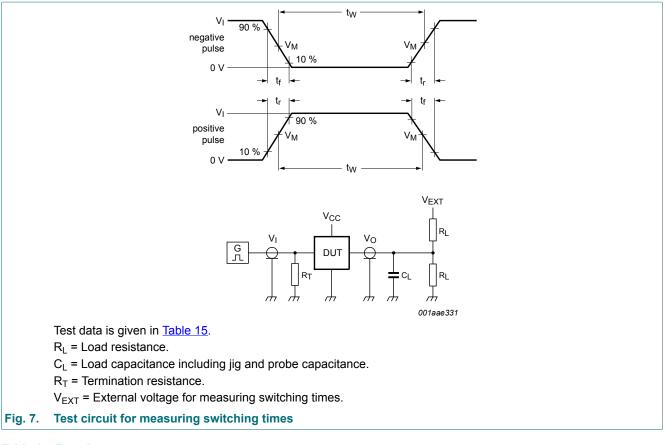


Table 15. Test data

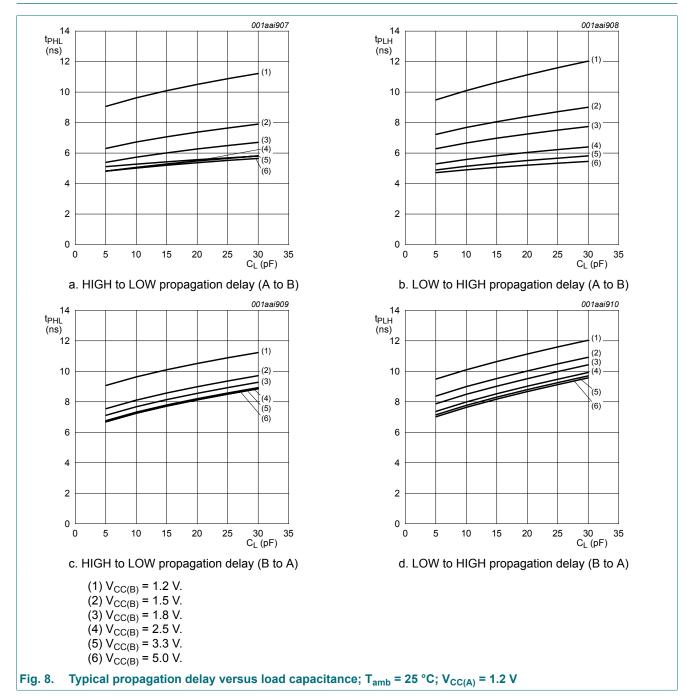
Supply voltage			Load		V _{EXT}				
$V_{CC(A)}, V_{CC(B)}$	V _I [1]	Δt/ΔV [2]	CL	R _L	t _{PLH} , t _{PHL}	t _{PZH} , t _{PHZ}	t _{PZL} , t _{PLZ} [3]		
1.2 V to 5.5 V	V _{CCI}	≤ 1.0 ns/V	15 pF	2 kΩ	open	GND	2V _{CCO}		

[1] V_{CCI} is the supply voltage associated with the data input port.

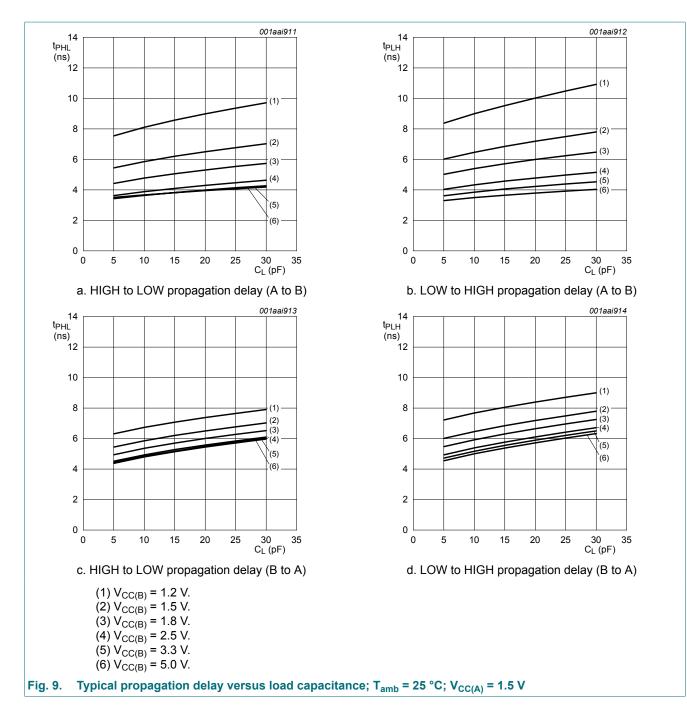
[2] dV/dt ≥ 1.0 V/ns.

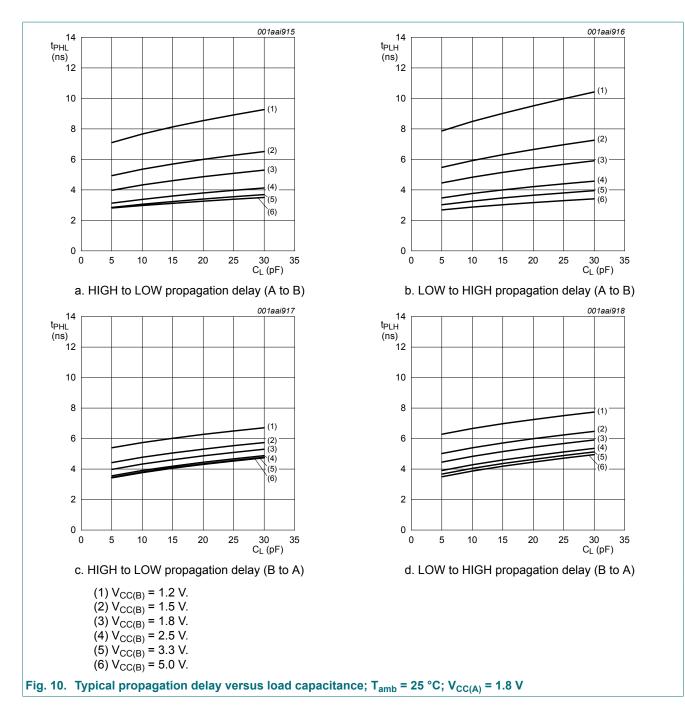
[3] V_{CCO} is the supply voltage associated with the output port.

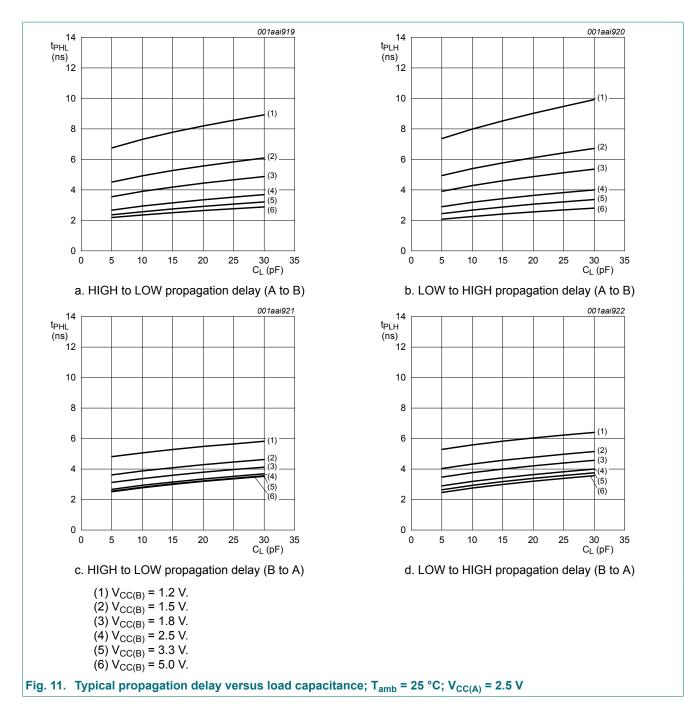
74LVC_LVCH2T45_Q100

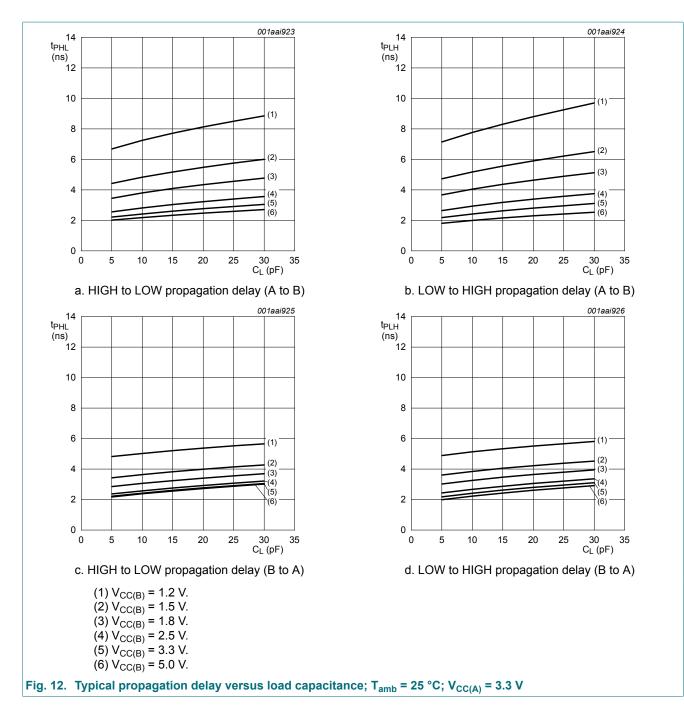


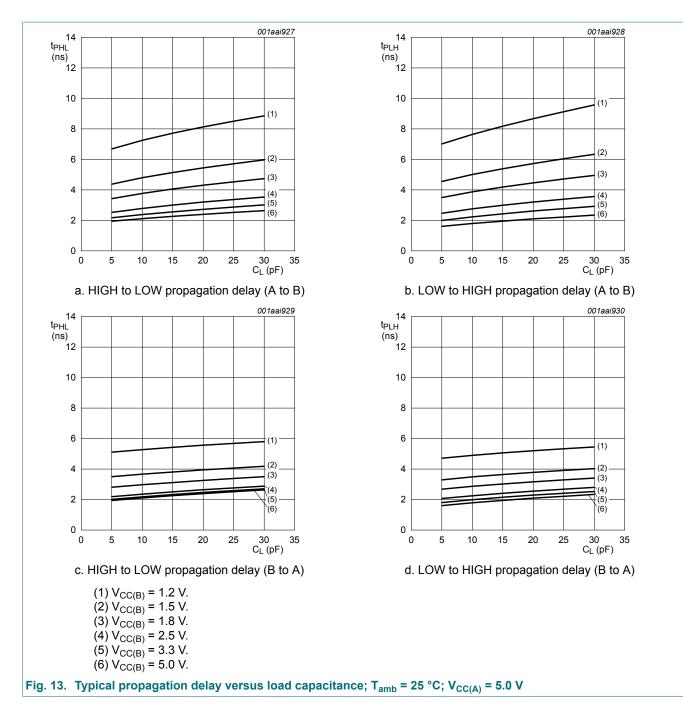
12. Typical propagation delay characteristics











13. Application information

13.1. Unidirectional logic level-shifting application

The circuit given in Fig. 14 is an example of the 74LVC2T45-Q100; 74LVCH2T45-Q100 being used in a unidirectional logic level-shifting application.

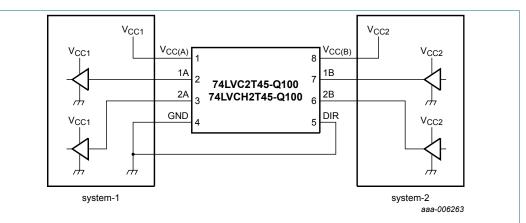


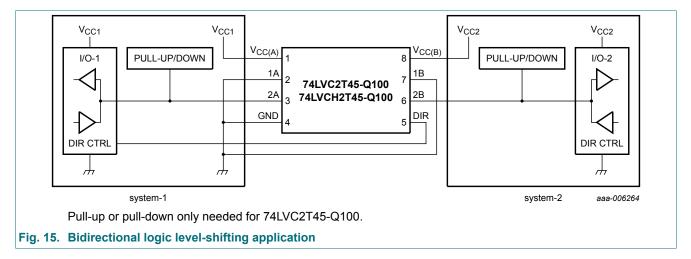
Fig. 14. Unidirectional logic level-shifting application

Table 16. Description of unidirectional logic level-shifting application

Pin	Name	Function	Description
1	V _{CC(A)}	V _{CC1}	supply voltage of system-1 (1.2 V to 5.5 V)
2	1A	OUT	output level depends on V _{CC1} voltage
3	2A	OUT	output level depends on V _{CC1} voltage
4	GND	GND	device GND
5	DIR	DIR	the GND (LOW level) determines B port to A port direction
6	2B	IN	input threshold value depends on V_{CC2} voltage
7	1B	IN	input threshold value depends on V_{CC2} voltage
8	V _{CC(B)}	V _{CC2}	supply voltage of system-2 (1.2 V to 5.5 V)

13.2. Bidirectional logic level-shifting application

Fig. 15 shows the 74LVC2T45-Q100; 74LVCH2T45-Q100 being used in a bidirectional logic level-shifting application. Since the device does not have an output enable pin, the system designer should take precautions to avoid bus contention between system-1 and system-2 when changing directions.



<u>Table 17</u> gives a sequence that will illustrate data transmission from system-1 to system-2 and then from system-2 to system-1.

Table 17. Description of bidirectional logic level-shifting application

H = HIGH voltage level;

L = LOW voltage level;

Z = high-impedance OFF-state.

State	DIR CTRL	I/O-1	I/O-2	Description
1	Н	output	input	system-1 data to system-2
2	Н	Z	Z	system-2 is getting ready to send data to system-1. I/O-1 and I/O-2 are disabled. The bus-line state depends on bus hold
3	L	Z	Z	DIR bit is set LOW. I/O-1 and I/O-2 still are disabled. The bus-line state depends on bus hold
4	L	input	output	system-2 data to system-1

13.3. Power-up considerations

The device is designed such that no special power-up sequence is required other than GND being applied first.

Table 18	. Typicaltotal	supply	current	(I _{CC(A)} +	· I _{CC(B)})
----------	----------------	--------	---------	-----------------------	------------------------

V _{CC(A)}	V _{CC(B)}					
	0 V	1.8 V	2.5 V	3.3 V	5.0 V	
0 V	0	< 1	< 1	< 1	< 1	μA
1.8 V	< 1	< 2	< 2	< 2	2	μA
2.5 V	< 1	< 2	< 2	< 2	< 2	μA
3.3 V	< 1	< 2	< 2	< 2	< 2	μA
5.0 V	< 1	2	< 2	< 2	< 2	μA

13.4. Enable times

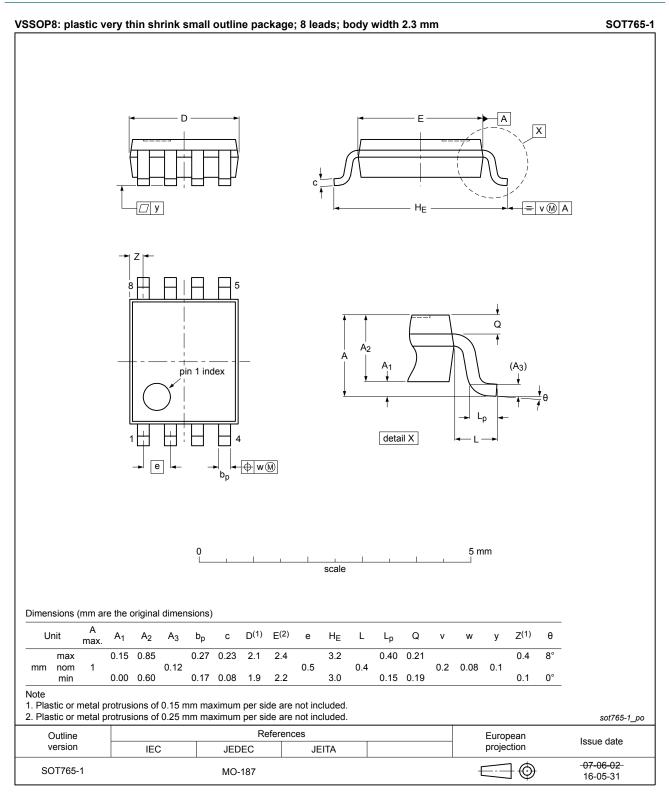
Calculate the enable times for the 74LVC2T45-Q100; 74LVCH2T45-Q100 using the following formulas:

- t_{PZH} (DIR to A) = t_{PLZ} (DIR to B) + t_{PLH} (B to A)
- t_{PZL} (DIR to A) = t_{PHZ} (DIR to B) + t_{PHL} (B to A)
- t_{PZH} (DIR to B) = t_{PLZ} (DIR to A) + t_{PLH} (A to B)
- t_{PZL} (DIR to B) = t_{PHZ} (DIR to A) + t_{PHL} (A to B)

In a bidirectional application, these enable times provide the maximum delay from the time the DIR bit is switched until an output is expected. For example, if the 74LVC2T45-Q100; 74LVCH2T45-Q100 initially is transmitting from A to B, then the DIR bit is switched, the B port of the device must be disabled before presenting it with an input. After the B port has been disabled, an input signal applied to it appears on the corresponding A port after the specified propagation delay.

74LVC_LVCH2T45_Q100

14. Package outline





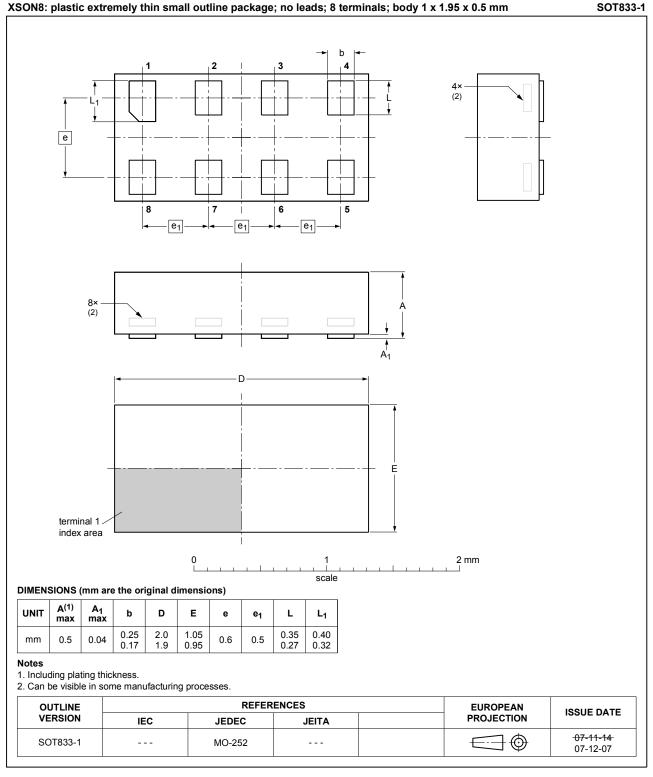


Fig. 17. Package outline SOT833-1 (XSON8)

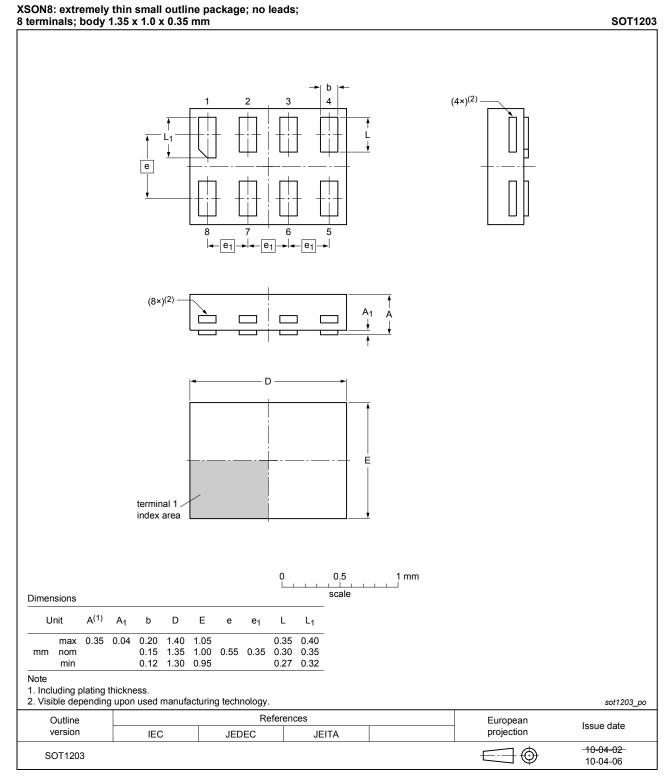


Fig. 18. Package outline SOT1203 (XSON8)

15. Abbreviations

Table 19. Abbreviations				
Acronym	Description			
DUT	Device Under Test			
ESD	ElectroStatic Discharge			
HBM	Human Body Model			
MIL	Military			
MM	Machine Model			

16. Revision history

Table 20. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes	
74LVC_LVCH2T45_Q100 v.3	20190128	Product data sheet	-	74LVC_LVCH2T45_Q100 v.2	
Modifications:	 Added type numbers 74LVC2T45GT-Q100 (SOT833-1) and 74LVC2T45GS-Q100 (SOT1203) 				
74LVC_LVCH2T45_Q100 v.2	20180813	Product data sheet	-	74LVC_LVCH2T45_Q100 v.1	
Modifications:	 The format of this data sheet has been redesigned to comply with the identity guidelines of Nexperia. Legal texts have been adapted to the new company name where appropriate. <u>Package outline drawing</u> (SOT765-1) modified. 				
74LVC_LVCH2T45_Q100 v.1	20130222	Product data sheet	-	-	

17. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

 Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at <u>https://www.nexperia.com</u>.

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